



Material Content Data Sheet



Sales Product Name	IAUC120N04S6L009	Issued	06. February 2023
MA#	MA005709493		
Package	PG-TDSON-8-34	Weight*	113.57 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.124	1.870	1.870	18703	18703
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.014	46.588	140	465882
	non noble metal	iron	7439-89-6	0.053	0.047		466	
	non noble metal	copper	7440-50-8	52.842	46.528		465276	
wire	noble metal	gold	7440-57-5	0.042	0.037	0.037	370	370
encapsulation	organic material	carbon black	1333-86-4	0.073	0.064	32.242	645	322415
	plastics	epoxy resin	-	5.785	5.094		50942	
	inorganic material	silicondioxide	60676-86-0	30.758	27.083		270829	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.386	1.386	13857	13857
plating	noble metal	silver	7440-22-4	0.209	0.184	0.184	1842	1842
solder	non noble metal	tin	7440-31-5	0.046	0.040	2.021	404	20214
	noble metal	silver	7440-22-4	0.057	0.051		505	
	non noble metal	lead	7439-92-1	2.192	1.930		19304	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.004	14.836	45	148361
	non noble metal	iron	7439-89-6	0.017	0.015		148	
	non noble metal	copper	7440-50-8	16.828	14.817		148168	
clip plating	noble metal	silver	7440-22-4	0.639	0.563	0.563	5626	5626
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.000	0.273	1	2729
	non noble metal	iron	7439-89-6	0.000	0.000		3	
	non noble metal	copper	7440-50-8	0.310	0.273		2726	
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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